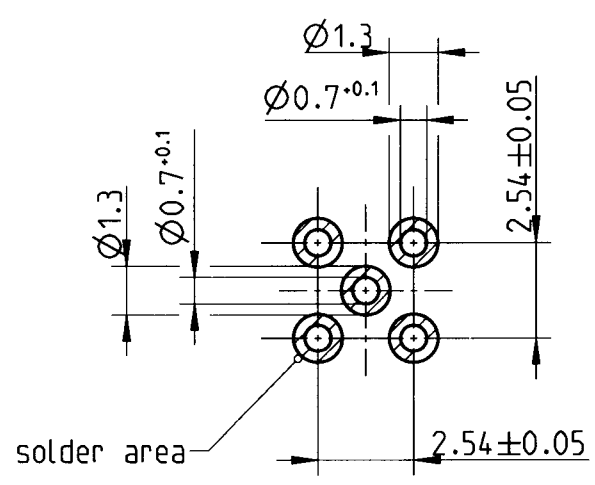


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Leiterplatten-Layout
PCB layout
B 35



A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector. Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector. In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Format: TCC-05-RE-A-Einzelteil
Date: 14.02.2001 10:08:58 AM
Version: 1.1

-METRIC-

ISO-Projektion
Methode E

Rosenberger Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER		general tolerance ISO 2768 RN 006-01 m-H dimensions <0.5 and symmetry		scale: 5:1 weight(g): surface(mm ²):
				material:
		date name drawn 15.02.2001 A_Nobis check 30.3.06 LL F appr.		title: Leiterplatten-Layout PCB layout
		dimensioning incl. finish		
e00	06-0194	S_Krautenbac	24.03.2006	drawing-no... MB_35
d00	02-0124	A_Nobis	06.10.2003	
c00	01-0266	V_Spitzauer	13.06.2001	sheet: 1 of: 1
rev. change-no name date		distribu- tion to: FE AZ QSM RMT . X		
				remarks: .